ON Semiconductor				10/15/2019
Base Part		H11D1M		Pb-free
Orderable Part		H11D1SR2VM	Total weight (mg)	464.903
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Coupling Gel	0.4	Dimethyl Cyclosiloxanes	69430-24-6	10
		Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3	90
Die	5.13	Silicon (Si)	7440-21-3	100
Die Attach	0.3	Silver (Ag)	7440-22-4	75
		Phenolic Resin-2	54208-63-8	25
Lead Frame	101.703	Silver (Ag)	7440-22-4	0.40018485
		Zinc (Zn)	7440-66-6	0.1996008
		Iron (Fe)	7439-89-6	2.59579363
		Copper (Cu)	7440-50-8	96.65398268
		Phosphorus (P)	7723-14-0	0.15043804
Mold Compound-White	327.22	Titanium Dioxide (TiO2)	13463-67-7	25
		Brominated Bisphenol A Diglycidyl Ether	40039-93-8	3
		Ortho Cresol Novolac Resin	29690-82-2	13.5
		Antimony Trioxide (Sb2O3)	1309-64-4	3
		Fused Silica (SiO2)	60676-86-0	50
		Phenolic Resin (Novolac)	9003-35-4	5.5
Plating	28.5	Tin (Sn)	7440-31-5	100
Wire Bond - Au	1.65	Gold (Au)	7440-57-5	100

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:

http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF